

# **PCA9548A Low Voltage 8-Channel I<sup>2</sup>C Switch With Reset** *Not Recommended for New Designs*

## 1 Features

- 1-of-8 Bidirectional Translating Switches
- I<sup>2</sup>C Bus and SMBus Compatible
- Active-Low Reset Input
- Three Hardware Address Pins for Use of up to Eight PCA9548A Devices on the I<sup>2</sup>C Bus
- Channel Selection Via I<sup>2</sup>C Bus
- Power-Up with All Switch Channels Deselected
- Low R<sub>ON</sub> Switches
- Allows Voltage-Level Translation Between 1.8-V, 2.5-V, 3.3-V, and 5-V Buses
- No Glitch on Power Up
- Supports Hot Insertion
- Low Standby Current
- Operating Power-Supply Voltage Range of 2.3 V to 5.5 V
- 5-V Tolerant Inputs
- 0 to 400-kHz Clock Frequency
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## 2 Applications

- Servers
- Routers (Telecom Switching Equipment)
- Factory Automation
- Products With I<sup>2</sup>C Slave Address Conflicts (e.g. Multiple, Identical Temp Sensors)

## 3 Description

The PCA9548A has eight bidirectional translating switches that can be controlled via the I<sup>2</sup>C bus. The SCL/SDA upstream pair fans out to eight downstream pairs, or channels. Any individual SCx/SDx channel or combination of channels can be selected, determined by the contents of the programmable control register.

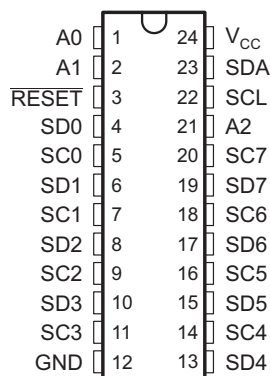
The system master can reset the PCA9548A in the event of a timeout or other improper operation by asserting a low in the RESET input. Similarly, the power-on reset deselected all channels and initializes the I<sup>2</sup>C/SMBus state machine. Asserting RESET causes the same reset/initialization to occur without powering down the part.

### Device information<sup>(1)</sup>

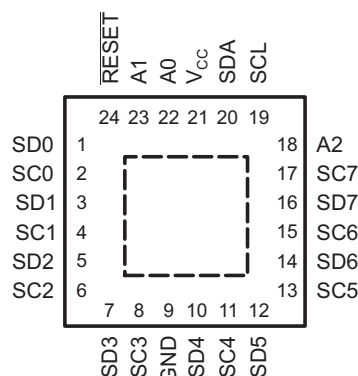
| DEVICE NAME | PACKAGE    | BODY SIZE (NOM)   |
|-------------|------------|-------------------|
| PCA9548A    | TSSOP (24) | 7.80 mm x 4.40 mm |
|             | VQFN (24)  | 4.00 mm x 4.00 mm |

(1) For all available packages, see the orderable addendum at the end of the datasheet.

**DB, DGV, DW, OR PW PACKAGE  
(TOP VIEW)**



**RGE PACKAGE  
(TOP VIEW)**



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## 4 Revision History

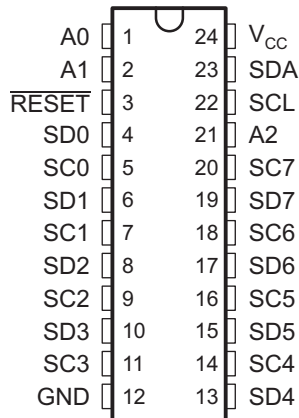
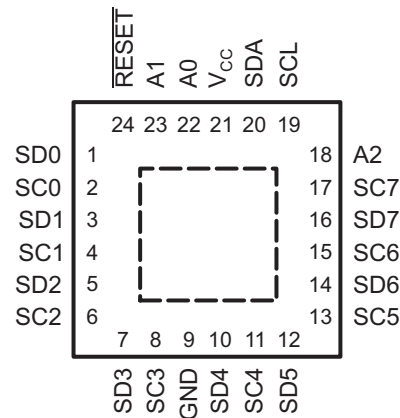
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision C (June 2007) to Revision D | Page      |
|---------------------------------------------------|-----------|
| • Added <b>RESET</b> Errata section. ....         | <b>11</b> |
| • Updated Typical Application schematic. ....     | <b>17</b> |
| • Added Power-On Reset Errata section. ....       | <b>20</b> |

## 5 Description (Continued)

The pass gates of the switches are constructed so that the  $V_{CC}$  pin can be used to limit the maximum high voltage, which is passed by the PCA9548A. This allows the use of different bus voltages on each pair, so that 1.8-V or 2.5-V or 3.3-V parts can communicate with 5-V parts, without any additional protection. External pull-up resistors pull the bus up to the desired voltage level for each channel. All I/O pins are 5-V tolerant.

## 6 Pin Configuration and Functions

**DB, DGV, DW, OR PW PACKAGE  
(TOP VIEW)**

**RGE PACKAGE  
(TOP VIEW)**

**Pin Functions**

| NAME     | PIN                  |           | DESCRIPTION                                                                          |
|----------|----------------------|-----------|--------------------------------------------------------------------------------------|
|          | NO.                  |           |                                                                                      |
|          | DW, DB, TPW, AND DGV | QFN (RGE) |                                                                                      |
| A0       | 1                    | 22        | Address input 0. Connect directly to $V_{CC}$ or ground.                             |
| A1       | 2                    | 23        | Address input 1. Connect directly to $V_{CC}$ or ground.                             |
| RESET    | 3                    | 24        | Active-low reset input. Connect to $V_{CC}$ through a pull-up resistor, if not used. |
| SD0      | 4                    | 1         | Serial data 0. Connect to $V_{CC}$ through a pull-up resistor.                       |
| SC0      | 5                    | 2         | Serial clock 0. Connect to $V_{CC}$ through a pull-up resistor.                      |
| SD1      | 6                    | 3         | Serial data 1. Connect to $V_{CC}$ through a pull-up resistor.                       |
| SC1      | 7                    | 4         | Serial clock 1. Connect to $V_{CC}$ through a pull-up resistor.                      |
| SC2      | 8                    | 5         | Serial data 2. Connect to $V_{CC}$ through a pull-up resistor.                       |
| SC2      | 9                    | 6         | Serial clock 2. Connect to $V_{CC}$ through a pull-up resistor.                      |
| SD3      | 10                   | 7         | Serial data 3. Connect to $V_{CC}$ through a pull-up resistor.                       |
| SC3      | 11                   | 8         | Serial clock 3. Connect to $V_{CC}$ through a pull-up resistor.                      |
| GND      | 12                   | 9         | Ground                                                                               |
| SD4      | 13                   | 10        | Serial data 4. Connect to $V_{CC}$ through a pull-up resistor.                       |
| SC4      | 14                   | 11        | Serial clock 4. Connect to $V_{CC}$ through a pull-up resistor.                      |
| SD5      | 15                   | 12        | Serial data 5. Connect to $V_{CC}$ through a pull-up resistor.                       |
| SC5      | 16                   | 13        | Serial clock 5. Connect to $V_{CC}$ through a pull-up resistor.                      |
| SD6      | 17                   | 14        | Serial data 6. Connect to $V_{CC}$ through a pull-up resistor.                       |
| SC6      | 18                   | 15        | Serial clock 6. Connect to $V_{CC}$ through a pull-up resistor.                      |
| SD7      | 19                   | 16        | Serial data 7. Connect to $V_{CC}$ through a pull-up resistor.                       |
| SC7      | 20                   | 17        | Serial clock 7. Connect to $V_{CC}$ through a pull-up resistor.                      |
| A2       | 21                   | 18        | Address input 2. Connect directly to $V_{CC}$ or ground.                             |
| SCL      | 22                   | 19        | Serial clock bus. Connect to $V_{CC}$ through a pull-up resistor.                    |
| SDA      | 23                   | 20        | Serial data bus. Connect to $V_{CC}$ through a pull-up resistor.                     |
| $V_{CC}$ | 24                   | 21        | Supply voltage                                                                       |

## 7 Specifications

### 7.1 Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

|                 |                                                                | MIN         | MAX  | UNIT |
|-----------------|----------------------------------------------------------------|-------------|------|------|
| V <sub>CC</sub> | Supply voltage range                                           | –0.5        | 7    | V    |
| V <sub>I</sub>  | Input voltage range <sup>(2)</sup>                             | –0.5        | 7    | V    |
| I <sub>I</sub>  | Input current                                                  |             | ±20  | mA   |
| I <sub>O</sub>  | Output current                                                 |             | ±25  | mA   |
| I <sub>CC</sub> | Supply current                                                 |             | ±100 | mA   |
| θ <sub>JA</sub> | Package thermal impedance, junction to free air <sup>(3)</sup> | DB package  |      | 63   |
|                 |                                                                | DGV package |      | 86   |
|                 |                                                                | DW package  |      | 46   |
|                 |                                                                | PW package  |      | 88   |
|                 |                                                                | RGE package |      | 45   |
| θ <sub>JP</sub> | Package thermal impedance, junction to pad                     | RGE package |      | 1.5  |
| T <sub>A</sub>  | Operating free-air temperature range                           | –40         | 85   | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-5.

### 7.2 Handling Ratings

|                    |                           | MIN                                                                                      | MAX | UNIT   |
|--------------------|---------------------------|------------------------------------------------------------------------------------------|-----|--------|
| T <sub>stg</sub>   | Storage temperature range | –65                                                                                      | 150 | °C     |
| V <sub>(ESD)</sub> | Electrostatic discharge   | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>              |     | 0 2000 |
|                    |                           | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup> |     | 0 1000 |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions<sup>(1)</sup>

|                 |                                | MIN                              | MAX | UNIT                                        |
|-----------------|--------------------------------|----------------------------------|-----|---------------------------------------------|
| V <sub>CC</sub> | Supply voltage                 | 2.3                              | 5.5 | V                                           |
| V <sub>IH</sub> | High-level input voltage       | SCL, SDA                         |     | 0.7 × V <sub>CC</sub> 6                     |
|                 |                                | A2–A0, $\overline{\text{RESET}}$ |     | 0.7 × V <sub>CC</sub> V <sub>CC</sub> + 0.5 |
| V <sub>IL</sub> | Low-level input voltage        | SCL, SDA                         |     | –0.5 0.3 × V <sub>CC</sub>                  |
|                 |                                | A2–A0, $\overline{\text{RESET}}$ |     | –0.5 0.3 × V <sub>CC</sub>                  |
| T <sub>A</sub>  | Operating free-air temperature | –40                              | 85  | °C                                          |

- (1) All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## 7.4 Electrical Characteristics

$V_{CC} = 2.3 \text{ V to } 3.6 \text{ V}$ , over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER                           |                                       |                            | TEST CONDITIONS                                                                     | V <sub>CC</sub>  | MIN | TYP <sup>(1)</sup> | MAX | UNIT |
|-------------------------------------|---------------------------------------|----------------------------|-------------------------------------------------------------------------------------|------------------|-----|--------------------|-----|------|
| V <sub>POR</sub>                    | Power-on reset voltage <sup>(2)</sup> |                            | No load, V <sub>I</sub> = V <sub>CC</sub> or GND                                    | V <sub>POR</sub> |     | 1.6                | 2.1 | V    |
| V <sub>O(SW)</sub>                  | Switch output voltage                 |                            | V <sub>I(SW)</sub> = V <sub>CC</sub> , I <sub>SWout</sub> = −100 μA                 | 5 V              |     | 3.6                |     | V    |
|                                     |                                       |                            |                                                                                     | 4.5 V to 5.5 V   |     | 2.6                | 4.5 |      |
|                                     |                                       |                            |                                                                                     | 3.3 V            |     | 1.9                |     |      |
|                                     |                                       |                            |                                                                                     | 3 V to 3.6 V     |     | 1.6                | 2.8 |      |
|                                     |                                       |                            |                                                                                     | 2.5 V            |     | 1.5                |     |      |
|                                     |                                       |                            |                                                                                     | 2.3 V to 2.7 V   |     | 1.1                | 2   |      |
| I <sub>OL</sub>                     | SDA                                   |                            | V <sub>OL</sub> = 0.4 V                                                             | 2.3 V to 5.5 V   | 3   | 6                  | mA  |      |
|                                     |                                       |                            | V <sub>OL</sub> = 0.6 V                                                             |                  | 6   | 9                  |     |      |
| I <sub>I</sub>                      | SCL, SDA                              |                            | V <sub>I</sub> = V <sub>CC</sub> or GND                                             | 2.3 V to 5.5 V   |     |                    | ±1  | μA   |
|                                     | SC7–SC0, SD7–SD0                      |                            |                                                                                     |                  |     |                    | ±1  |      |
|                                     | A2–A0                                 |                            |                                                                                     |                  |     |                    | ±1  |      |
|                                     | RESET                                 |                            |                                                                                     |                  |     |                    | ±1  |      |
| I <sub>CC</sub>                     | Operating mode                        | f <sub>SCL</sub> = 400 kHz | V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0                         | 5.5 V            |     | 50                 | 80  | μA   |
|                                     |                                       |                            |                                                                                     | 3.6 V            |     | 20                 | 35  |      |
|                                     |                                       |                            |                                                                                     | 2.7 V            |     | 11                 | 20  |      |
|                                     |                                       | f <sub>SCL</sub> = 100 kHz | V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0                         | 5.5 V            |     | 9                  | 30  |      |
|                                     |                                       |                            |                                                                                     | 3.6 V            |     | 6                  | 15  |      |
|                                     |                                       |                            |                                                                                     | 2.7 V            |     | 4                  | 8   |      |
|                                     | Standby mode                          | Low inputs                 | V <sub>I</sub> = GND, I <sub>O</sub> = 0                                            | 5.5 V            |     | 0.2                | 1   |      |
|                                     |                                       |                            |                                                                                     | 3.6 V            |     | 0.1                | 1   |      |
|                                     |                                       |                            |                                                                                     | 2.7 V            |     | 0.1                | 1   |      |
|                                     |                                       | High inputs                | V <sub>I</sub> = V <sub>CC</sub> , I <sub>O</sub> = 0                               | 5.5 V            |     | 0.2                | 1   |      |
|                                     |                                       |                            |                                                                                     | 3.6 V            |     | 0.1                | 1   |      |
|                                     |                                       |                            |                                                                                     | 2.7 V            |     | 0.1                | 1   |      |
| ΔI <sub>CC</sub>                    | Supply-current change                 | SCL, SDA                   | SCL or SDA input at 0.6 V, Other inputs at V <sub>CC</sub> or GND                   | 2.3 V to 5.5 V   | 3   | 20                 | μA  |      |
|                                     |                                       |                            | SCL or SDA input at V <sub>CC</sub> − 0.6 V, Other inputs at V <sub>CC</sub> or GND |                  | 3   | 20                 |     |      |
| C <sub>i</sub>                      | A2–A0                                 |                            | V <sub>I</sub> = V <sub>CC</sub> or GND                                             | 2.3 V to 5.5 V   | 4   | 5                  | pF  |      |
|                                     | RESET                                 |                            |                                                                                     |                  | 4   | 5                  |     |      |
|                                     | SCL                                   |                            |                                                                                     |                  | 20  | 28                 |     |      |
| C <sub>io(off)</sub> <sup>(3)</sup> | SDA                                   |                            | V <sub>I</sub> = V <sub>CC</sub> or GND, Switch OFF                                 | 2.3 V to 5.5 V   | 20  | 28                 | pF  |      |
|                                     | SC7–SC0, SD7–SD0                      |                            |                                                                                     |                  | 5.5 | 7.5                |     |      |
| R <sub>ON</sub>                     | Switch-on resistance                  |                            | V <sub>O</sub> = 0.4 V, I <sub>O</sub> = 15 mA                                      | 4.5 V to 5.5 V   | 4   | 10                 | 20  | Ω    |
|                                     |                                       |                            |                                                                                     | 3 V to 3.6 V     | 5   | 12                 | 30  |      |
|                                     |                                       |                            | V <sub>O</sub> = 0.4 V, I <sub>O</sub> = 10 mA                                      | 2.3 V to 2.7 V   | 7   | 15                 | 45  |      |

(1) All typical values are at nominal supply voltage (2.5-V, 3.3-V, or 5-V  $V_{CC}$ ),  $T_A = 25^\circ\text{C}$ .

(2) The power-on reset circuit resets the I<sup>2</sup>C bus logic with  $V_{CC} < V_{POR}$ .  $V_{CC}$  must be lowered to 0.2 V to reset the device.

(3)  $C_{IO(ON)}$  depends on internal capacitance and external capacitance added to the SCn lines when channels(s) are ON.

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## 7.5 I<sup>2</sup>C Interface Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

|                        |                                                               |                                           | STANDARD MODE<br>I <sup>2</sup> C BUS |      | FAST MODE<br>I <sup>2</sup> C BUS     |     | UNIT |
|------------------------|---------------------------------------------------------------|-------------------------------------------|---------------------------------------|------|---------------------------------------|-----|------|
|                        |                                                               |                                           | MIN                                   | MAX  | MIN                                   | MAX |      |
| f <sub>SCL</sub>       | I <sup>2</sup> C clock frequency                              |                                           | 0                                     | 100  | 0                                     | 400 | kHz  |
| t <sub>SCH</sub>       | I <sup>2</sup> C clock high time                              |                                           | 4                                     |      | 0.6                                   |     | μs   |
| t <sub>SCL</sub>       | I <sup>2</sup> C clock low time                               |                                           | 4.7                                   |      | 1.3                                   |     | μs   |
| t <sub>SP</sub>        | I <sup>2</sup> C spike time                                   |                                           |                                       | 50   |                                       | 50  | ns   |
| t <sub>SDS</sub>       | I <sup>2</sup> C serial-data setup time                       |                                           | 250                                   |      | 100                                   |     | ns   |
| t <sub>SDH</sub>       | I <sup>2</sup> C serial-data hold time                        |                                           | 0 <sup>(1)</sup>                      |      | 0 <sup>(1)</sup>                      |     | μs   |
| t <sub>ICR</sub>       | I <sup>2</sup> C input rise time                              |                                           |                                       | 1000 | 20 + 0.1C <sub>b</sub> <sup>(2)</sup> | 300 | ns   |
| t <sub>ICF</sub>       | I <sup>2</sup> C input fall time                              |                                           |                                       | 300  | 20 + 0.1C <sub>b</sub> <sup>(2)</sup> | 300 | ns   |
| t <sub>OCF</sub>       | I <sup>2</sup> C output (SDn) fall time (10-pF to 400-pF bus) |                                           |                                       | 300  | 20 + 0.1C <sub>b</sub> <sup>(2)</sup> | 300 | ns   |
| t <sub>BUF</sub>       | I <sup>2</sup> C bus free time between stop and start         |                                           | 4.7                                   |      | 1.3                                   |     | μs   |
| t <sub>STS</sub>       | I <sup>2</sup> C start or repeated start condition setup      |                                           | 4.7                                   |      | 0.6                                   |     | μs   |
| t <sub>STH</sub>       | I <sup>2</sup> C start or repeated start condition hold       |                                           | 4                                     |      | 0.6                                   |     | μs   |
| t <sub>SPS</sub>       | I <sup>2</sup> C stop condition setup                         |                                           | 4                                     |      | 0.6                                   |     | μs   |
| t <sub>VDL(Data)</sub> | Valid-data time (high to low) <sup>(3)</sup>                  | SCL low to SDA output low valid           |                                       | 1    |                                       | 1   | μs   |
| t <sub>VdH(Data)</sub> | Valid-data time (low to high) <sup>(3)</sup>                  | SCL low to SDA output high valid          |                                       | 0.6  |                                       | 0.6 | μs   |
| t <sub>VD(ack)</sub>   | Valid-data time of ACK condition                              | ACK signal from SCL low to SDA output low |                                       | 1    |                                       | 1   | μs   |
| C <sub>b</sub>         | I <sup>2</sup> C bus capacitive load                          |                                           |                                       | 400  |                                       | 400 | pF   |

- (1) A device internally must provide a hold time of at least 300 ns for the SDA signal (referred to the V<sub>IH</sub> min of the SCL signal), to bridge the undefined region of the falling edge of SCL.
- (2) C<sub>b</sub> = total bus capacitance of one bus line in pF
- (3) Data taken using a 1-kΩ pull-up resistor and 50-pF load (see Figure 2)

## 7.6 Switching Characteristics

over recommended operating free-air temperature range, C<sub>L</sub> ≤ 100 pF (unless otherwise noted) (see Figure 1)

| PARAMETER                       |                        | FROM<br>(INPUT)                                | TO<br>(OUTPUT) | MIN        | MAX | UNIT |
|---------------------------------|------------------------|------------------------------------------------|----------------|------------|-----|------|
| t <sub>pd</sub> <sup>(1)</sup>  | Propagation delay time | R <sub>ON</sub> = 20 Ω, C <sub>L</sub> = 15 pF | SDA or SCL     | SDn or SCn | 0.3 | ns   |
|                                 |                        | R <sub>ON</sub> = 20 Ω, C <sub>L</sub> = 50 pF |                |            | 1   |      |
| t <sub>rst</sub> <sup>(2)</sup> | RESET time (SDA clear) |                                                | RESET          | SDA        | 500 | ns   |

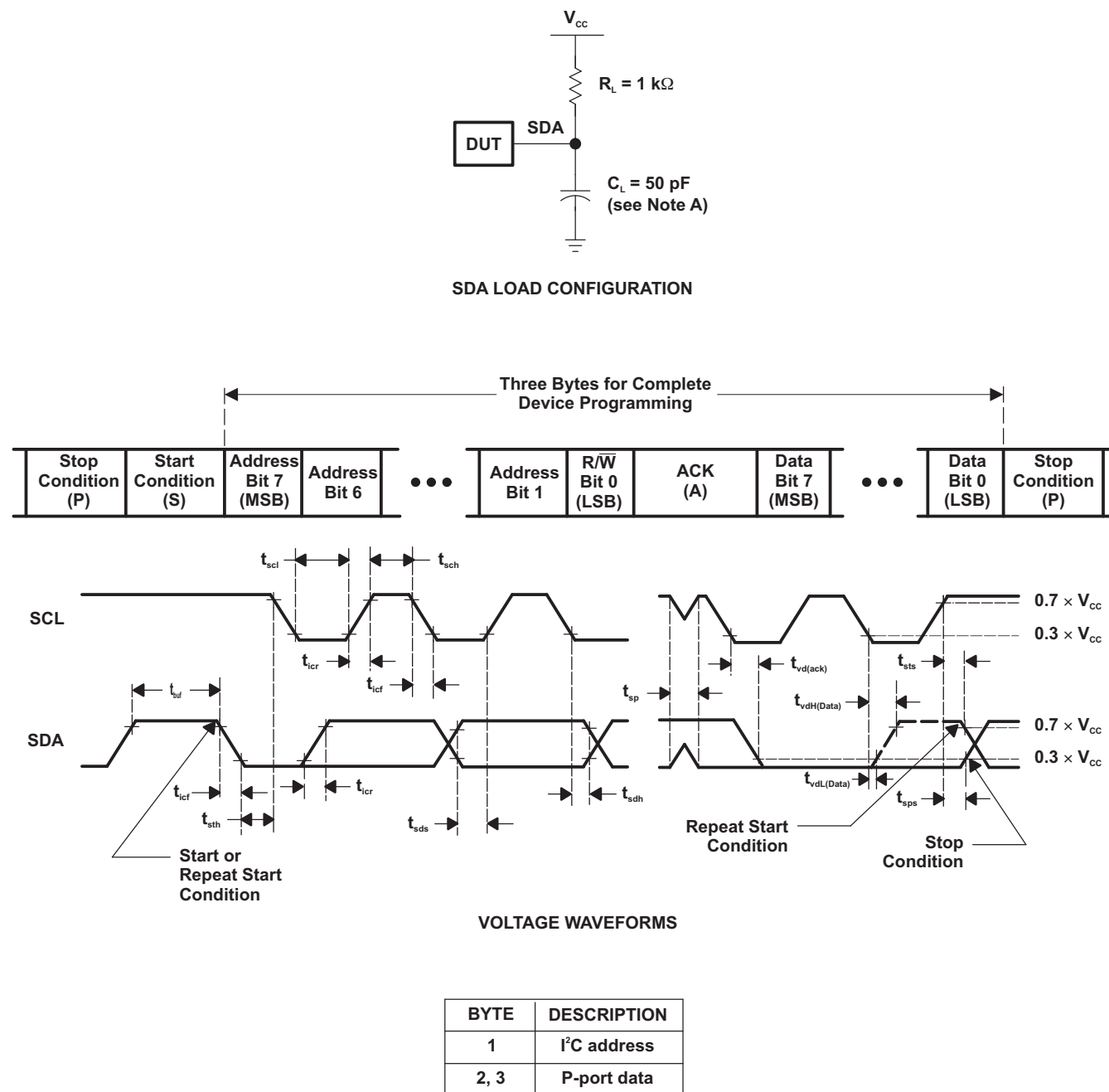
- (1) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
- (2) t<sub>rst</sub> is the propagation delay measured from the time the RESET pin is first asserted low to the time the SDA pin is asserted high, signaling a stop condition. It must be a minimum of t<sub>WL</sub>.

## 7.7 Reset Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER             |                                   |  | MIN | MAX | UNIT |
|-----------------------|-----------------------------------|--|-----|-----|------|
| t <sub>W(L)</sub>     | Pulse duration, RESET low         |  | 6   |     | ns   |
| t <sub>REC(STA)</sub> | Recovery time from RESET to start |  | 0   |     | ns   |

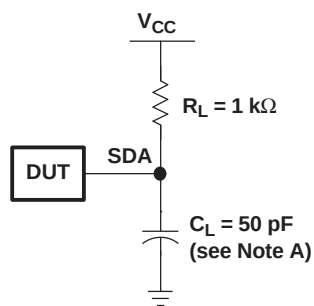
## 8 Parameter Measurement Information



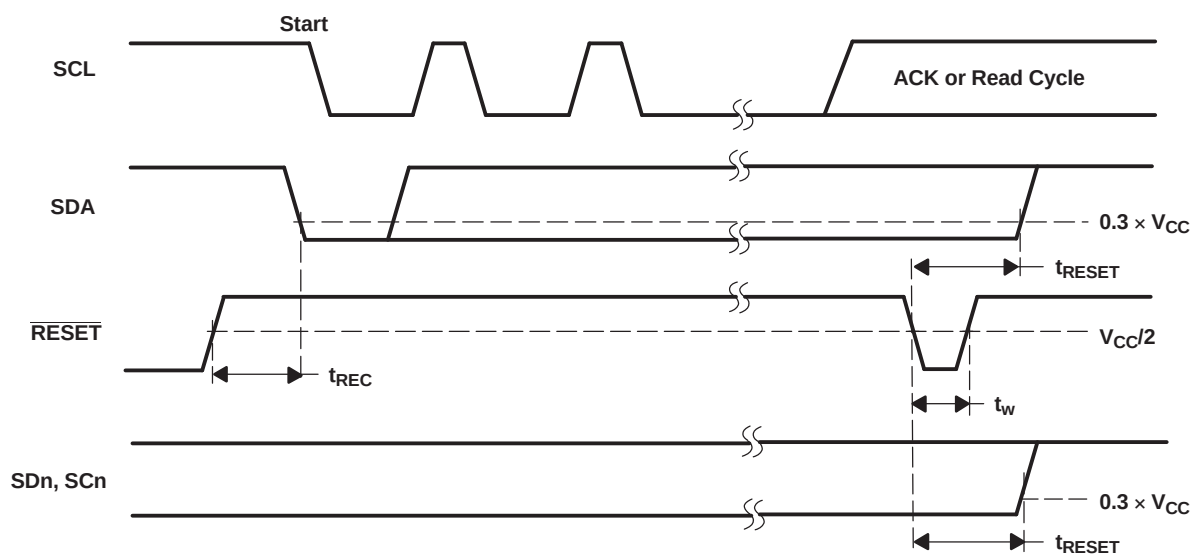
- A.  $C_L$  includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r/t_f \leq 30 \text{ ns}$ .
- C. Not all parameters and waveforms are applicable to all devices.

**Figure 1. I<sup>2</sup>C Load Circuit and Voltage Waveforms**

## Parameter Measurement Information (continued)



SDA LOAD CONFIGURATION



- A.  $C_L$  includes probe and jig capacitance.
- B. All inputs are supplied by generators having the following characteristics:  $PRR \leq 10\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r/t_f \leq 30\text{ ns}$ .
- C. I/Os are configured as inputs.
- D. Not all parameters and waveforms are applicable to all devices.

Figure 2. Reset Load Circuit and Voltage Waveforms



## 9 Detailed Description

### 9.1 Overview

The PCA9548A is a 8-channel, bidirectional translating I<sup>2</sup>C switch. The master SCL/SDA signal pair is directed to eight channels of slave devices, SC0/SD0-SC3/SD3. Any individual downstream channel can be selected as well as any combination of the eight channels.

The device offers an active-low  $\overline{\text{RESET}}$  input which resets the state machine and allows the PCA9548A to recover should one of the downstream I<sup>2</sup>C buses get stuck in a low state. The state machine of the device can also be reset by cycling the power supply, V<sub>CC</sub>, also known as a power-on reset (POR). Both the  $\overline{\text{RESET}}$  function and a POR will cause all channels to be deselected.

The connections of the I<sup>2</sup>C data path are controlled by the same I<sup>2</sup>C master device that is switched to communicate with multiple I<sup>2</sup>C slaves. After the successful acknowledgment of the slave address (hardware selectable by A0 and A1 pins), a single 8-bit control register is written to or read from to determine the selected channels.

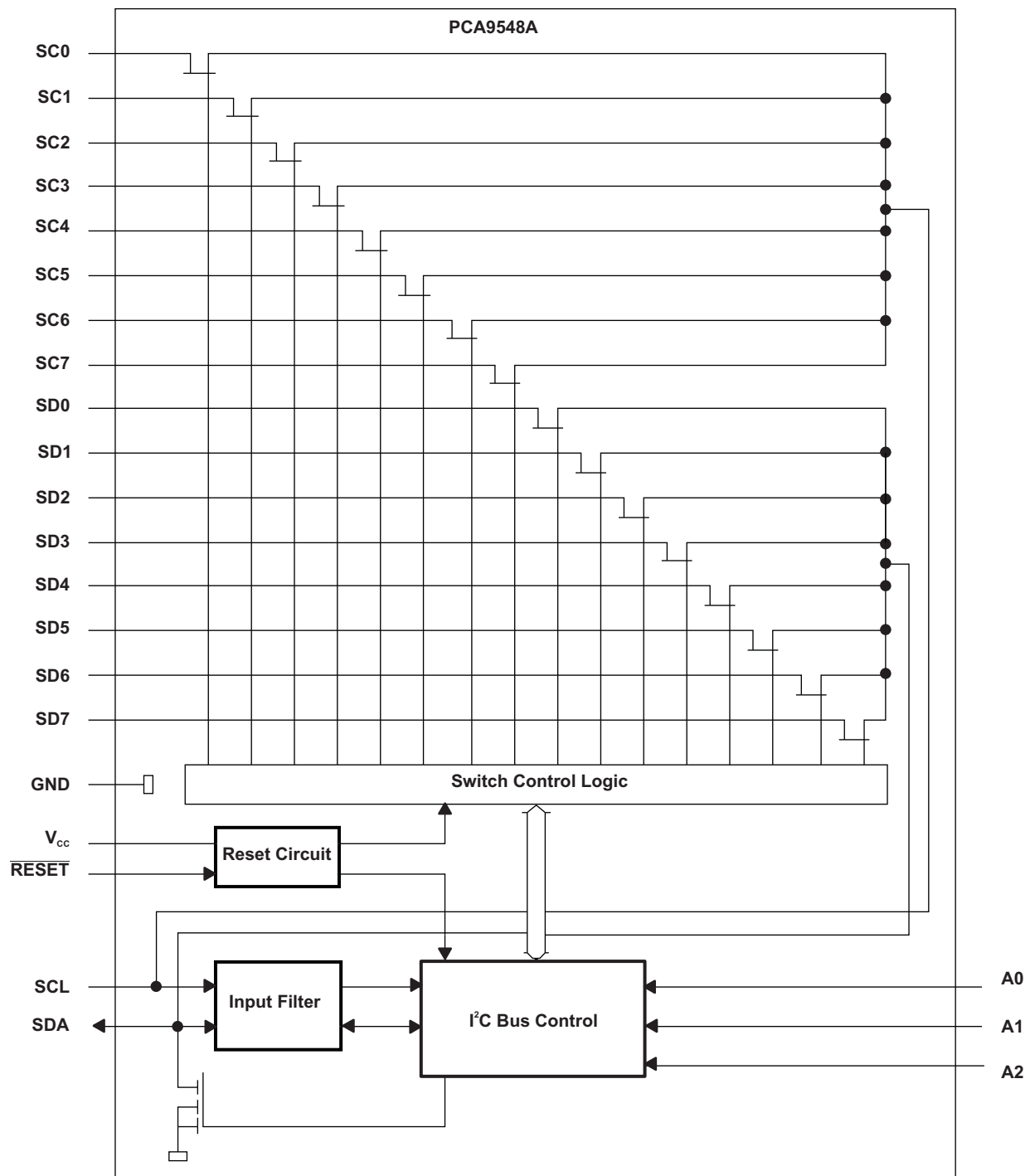
The PCA9548A may also be used for voltage translation, allowing the use of different bus voltages on each SCn/SDn pair such that 1.8-V, 2.5-V, or 3.3-V parts can communicate with 5-V parts. This is achieved by using external pull-up resistors to pull the bus up to the desired voltage for the master and each slave channel.

## PCA9548A

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### 9.2 Functional Block Diagram



### 9.3 Feature Description

The PCA9548A is an 8-channel, bidirectional translating switch for I<sup>2</sup>C buses that supports Standard-Mode (100 kHz) and Fast-Mode (400 kHz) operation. The PCA9548A features I<sup>2</sup>C control using a single 8-bit control register in which each bit controls the enabling and disabling for one of the 8 switch channels of I<sup>2</sup>C data flow. Depending on the application, voltage translation of the I<sup>2</sup>C bus can also be achieved using the PCA9548A to allow 1.8-V, 2.5-V, or 3.3-V parts to communicate with 5-V parts. Additionally, in the event that communication on the I<sup>2</sup>C bus enters a fault state, the PCA9548A can be reset to resume normal operation using the  $\overline{\text{RESET}}$  pin feature or by a power-on reset which results from cycling power to the device.

### 9.4 Device Functional Modes

#### 9.4.1 $\overline{\text{RESET}}$ Input

The  $\overline{\text{RESET}}$  input is an active-low signal that may be used to recover from a bus-fault condition. When this signal is asserted low for a minimum of  $t_{WL}$ , the PCA9548A resets its registers and I<sup>2</sup>C state machine and deselects all channels. The  $\overline{\text{RESET}}$  input must be connected to V<sub>CC</sub> through a pull-up resistor.

##### 9.4.1.1 $\overline{\text{RESET}}$ Errata

If RESET voltage set higher than VCC, current will flow from RESET pin to VCC pin.

#### System Impact

VCC will be pulled above its regular voltage level

#### System Workaround

Design such that  $\overline{\text{RESET}}$  voltage is same or lower than VCC

#### 9.4.2 Power-On Reset

When power (from 0 V) is applied to V<sub>CC</sub>, an internal power-on reset holds the PCA9548A in a reset condition until V<sub>CC</sub> has reached V<sub>POR</sub>. At that point, the reset condition is released and the PCA9548A registers and I<sup>2</sup>C state machine initialize to their default states. After that, V<sub>CC</sub> must be lowered to below V<sub>POR</sub> and then back up to the operating voltage for a power-reset cycle.

Refer to the [Power-On Reset Errata](#) section.

### 9.5 Programming

#### 9.5.1 I<sup>2</sup>C Interface

The bidirectional I<sup>2</sup>C bus consists of the serial clock (SCL) and serial data (SDA) lines. Both lines must be connected to a positive supply through a pull-up resistor when connected to the output stages of a device. Data transfer may be initiated only when the bus is not busy.

I<sup>2</sup>C communication with this device is initiated by a master sending a start condition, a high-to-low transition on the SDA input/output while the SCL input is high (see [Figure 3](#)). After the start condition, the device address byte is sent, most significant bit (MSB) first, including the data direction bit (R/W).

After receiving the valid address byte, this device responds with an acknowledge (ACK), a low on the SDA input/output during the high of the ACK-related clock pulse. The address inputs (A0–A2) of the slave device must not be changed between the start and the stop conditions.

On the I<sup>2</sup>C bus, only one data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the high pulse of the clock period, as changes in the data line at this time are interpreted as control commands (start or stop) (see [Figure 4](#)).

A stop condition, a low-to-high transition on the SDA input/output while the SCL input is high, is sent by the master (see [Figure 3](#)).

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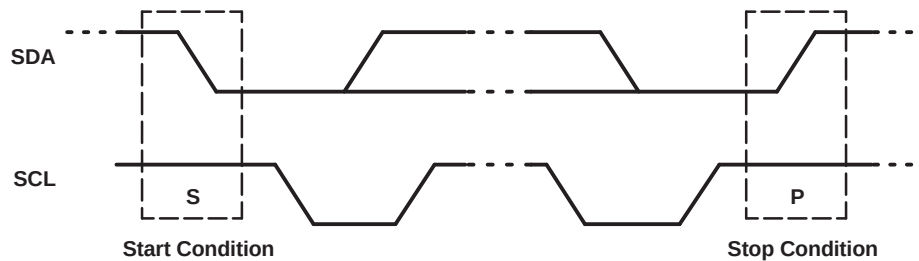
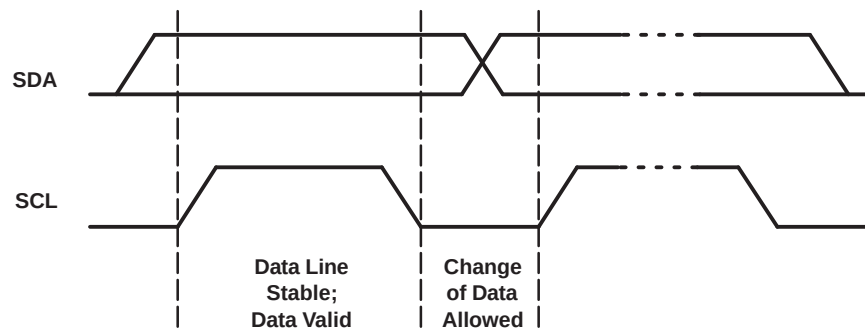
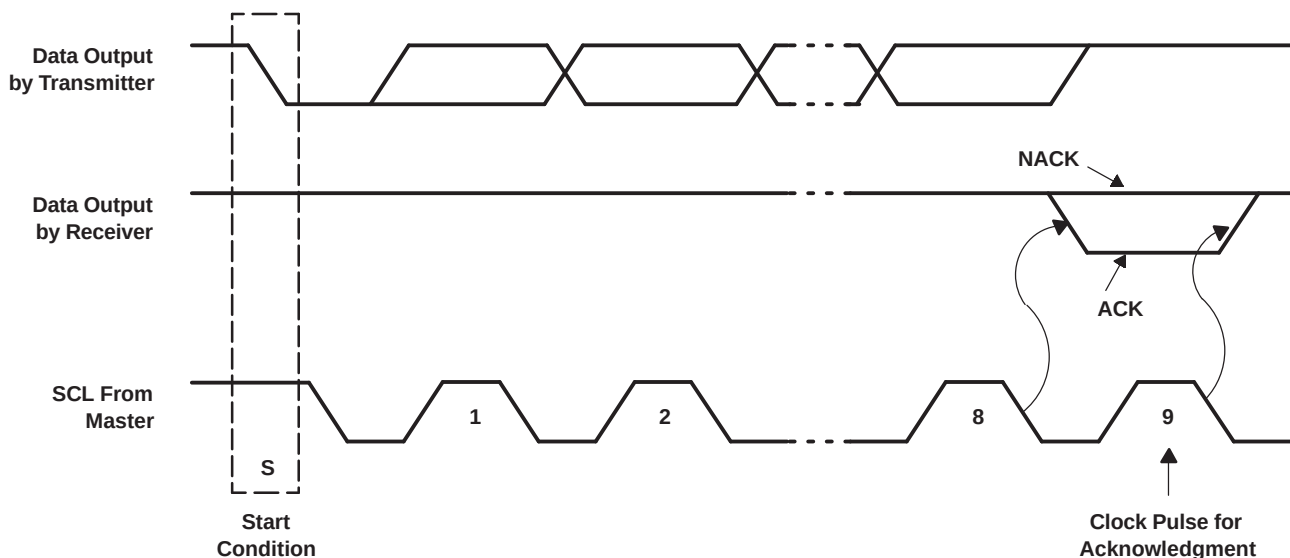
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**Programming (continued)**

Any number of data bytes can be transferred from the transmitter to receiver between the start and the stop conditions. Each byte of eight bits is followed by one ACK bit. The transmitter must release the SDA line before the receiver can send an ACK bit. The device that acknowledges must pull down the SDA line during the ACK clock pulse so that the SDA line is stable low during the high pulse of the ACK-related clock period (see [Figure 5](#)). When a slave receiver is addressed, it must generate an ACK after each byte is received. Similarly, the master must generate an ACK after each byte that it receives from the slave transmitter. Setup and hold times must be met to ensure proper operation.

A master receiver signals an end of data to the slave transmitter by not generating an acknowledge (NACK) after the last byte has been clocked out of the slave. This is done by the master receiver by holding the SDA line high. In this event, the transmitter must release the data line to enable the master to generate a stop condition.

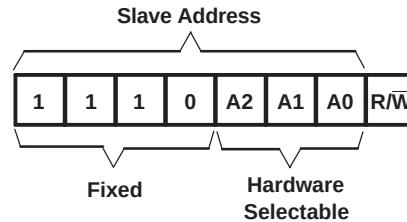
**Figure 3. Definition of Start and Stop Conditions****Figure 4. Bit Transfer****Figure 5. Acknowledgment on I²C Bus**

## Programming (continued)

### 9.5.2 Register Map

#### 9.5.2.1 Device Address

Figure 6 shows the address byte of the PCA9548A.



**Figure 6. PCA9548A Address**

The last bit of the slave address defines the operation (read or write) to be performed. When it is high (1), a read is selected, while a low (0) selects a write operation.

**Table 1. Address Reference**

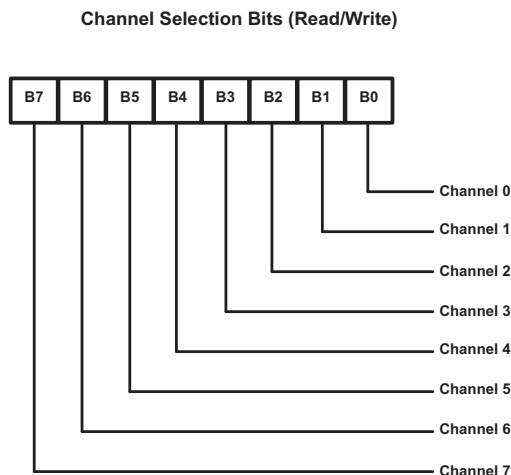
| INPUTS |    |    | I <sup>2</sup> C BUS SLAVE ADDRESS |
|--------|----|----|------------------------------------|
| A2     | A1 | A0 |                                    |
| L      | L  | L  | 112 (decimal), 70 (hexadecimal)    |
| L      | L  | H  | 113 (decimal), 71 (hexadecimal)    |
| L      | H  | L  | 114 (decimal), 72 (hexadecimal)    |
| L      | H  | H  | 115 (decimal), 73 (hexadecimal)    |
| H      | L  | L  | 116 (decimal), 74 (hexadecimal)    |
| H      | L  | H  | 117 (decimal), 75 (hexadecimal)    |
| H      | H  | L  | 118 (decimal), 76 (hexadecimal)    |
| H      | H  | H  | 119 (decimal), 77 (hexadecimal)    |

#### 9.5.2.2 Control Register

Following the successful acknowledgment of the address byte, the bus master sends a command byte that is stored in the control register in the PCA9548A (see Figure 7). This register can be written and read via the I<sup>2</sup>C bus. Each bit in the command byte corresponds to a SCn/SDn channel and a high (or 1) selects this channel. Multiple SCn/SDn channels may be selected at the same time. When a channel is selected, the channel becomes active after a stop condition has been placed on the I<sup>2</sup>C bus. This ensures that all SCn/SDn lines are in a high state when the channel is made active, so that no false conditions are generated at the time of connection. A stop condition always must occur immediately after the acknowledge cycle. If multiple bytes are received by the PCA9548A, it saves the last byte received.

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[www.ti.com](http://www.ti.com)**Figure 7. Control Register****Table 2. Command Byte Definition**

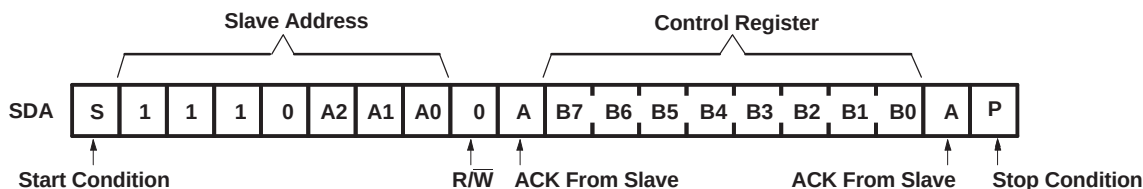
| CONTROL REGISTER BITS |    |    |    |    |    |    |    | COMMAND                                           |
|-----------------------|----|----|----|----|----|----|----|---------------------------------------------------|
| B7                    | B6 | B5 | B4 | B3 | B2 | B1 | B0 |                                                   |
| X                     | X  | X  | X  | X  | X  | X  | 0  | Channel 0 disabled                                |
|                       |    |    |    |    |    |    | 1  | Channel 0 enabled                                 |
| X                     | X  | X  | X  | X  | X  | 0  | X  | Channel 1 disabled                                |
|                       |    |    |    |    |    | 1  |    | Channel 1 enabled                                 |
| X                     | X  | X  | X  | X  | 0  | X  | X  | Channel 2 disabled                                |
|                       |    |    |    |    | 1  |    |    | Channel 2 enabled                                 |
| X                     | X  | X  | X  | 0  | X  | X  | X  | Channel 3 disabled                                |
|                       |    |    |    | 1  |    |    |    | Channel 3 enabled                                 |
| X                     | X  | X  | 0  | X  | X  | X  | X  | Channel 4 disabled                                |
|                       |    |    | 1  |    |    |    |    | Channel 4 enabled                                 |
| X                     | X  | 0  | X  | X  | X  | X  | X  | Channel 5 disabled                                |
|                       |    | 1  |    |    |    |    |    | Channel 5 enabled                                 |
| X                     | 0  | X  | X  | X  | X  | X  | X  | Channel 6 disabled                                |
|                       | 1  |    |    |    |    |    |    | Channel 6 enabled                                 |
| 0                     | X  | X  | X  | X  | X  | X  | X  | Channel 7 disabled                                |
| 1                     |    |    |    |    |    |    |    | Channel 7 enabled                                 |
| 0                     | 0  | 0  | 0  | 0  | 0  | 0  | 0  | No channel selected, power-up/reset default state |

### 9.5.2.3 Bus Transactions

Data is exchanged between the master and PCA9548A through write and read commands.

#### 9.5.2.3.1 Writes

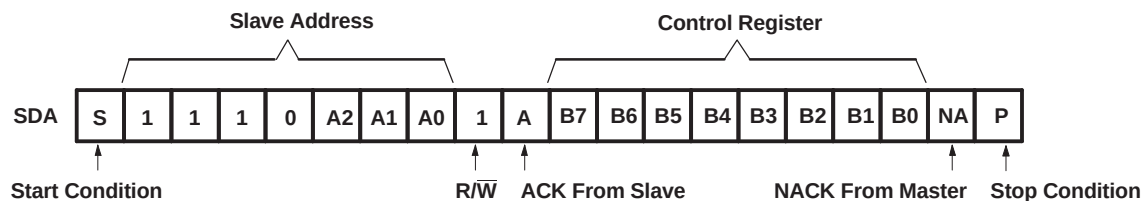
Data is transmitted to the PCA9548A by sending the device address and setting the least-significant bit (LSB) to a logic 0 (see [Figure 6](#) for device address). The command byte is sent after the address and determines which SCn/SDn channel receives the data that follows the command byte (see [Figure 8](#)). There is no limitation on the number of data bytes sent in one write transmission.



**Figure 8. Write to Control Register**

#### 9.5.2.3.2 Reads

The bus master first must send the PCA9548A address with the LSB set to a logic 1 (see [Figure 6](#) for device address). The command byte is sent after the address and determines which SCn/SDn channel is accessed. After a restart, the device address is sent again, but this time, the LSB is set to a logic 1. Data from the SCn/SDn channel defined by the command byte then is sent by the PCA9548A (see [Figure 9](#)). After a restart, the value of the SCn/SDn channel defined by the command byte matches the SCn/SDn channel being accessed when the restart occurred. Data is clocked into the SCn/SDn channel on the rising edge of the ACK clock pulse. There is no limitation on the number of data bytes received in one read transmission, but when the final byte is received, the bus master must not acknowledge the data.



**Figure 9. Read From Control Register**

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## 10 Application and Implementation

### 10.1 Application Information

Applications of the PCA9548A will contain an I<sup>2</sup>C (or SMBus) master device and up to eight I<sup>2</sup>C slave devices. The downstream channels are ideally used to resolve I<sup>2</sup>C slave address conflicts. For example, if eight identical digital temperature sensors are needed in the application, one sensor can be connected at each channel: 0, 1, 2, and 3. When the temperature at a specific location needs to be read, the appropriate channel can be enabled and all other channels switched off, the data can be retrieved, and the I<sup>2</sup>C master can move on and read the next channel.

In an application where the I<sup>2</sup>C bus will contain many additional slave devices that do not result in I<sup>2</sup>C slave address conflicts, these slave devices can be connected to any desired channel to distribute the total bus capacitance across multiple channels. If multiple switches will be enabled simultaneously, additional design requirements must be considered (See [Design Requirements](#) and [Detailed Design Procedure](#)).

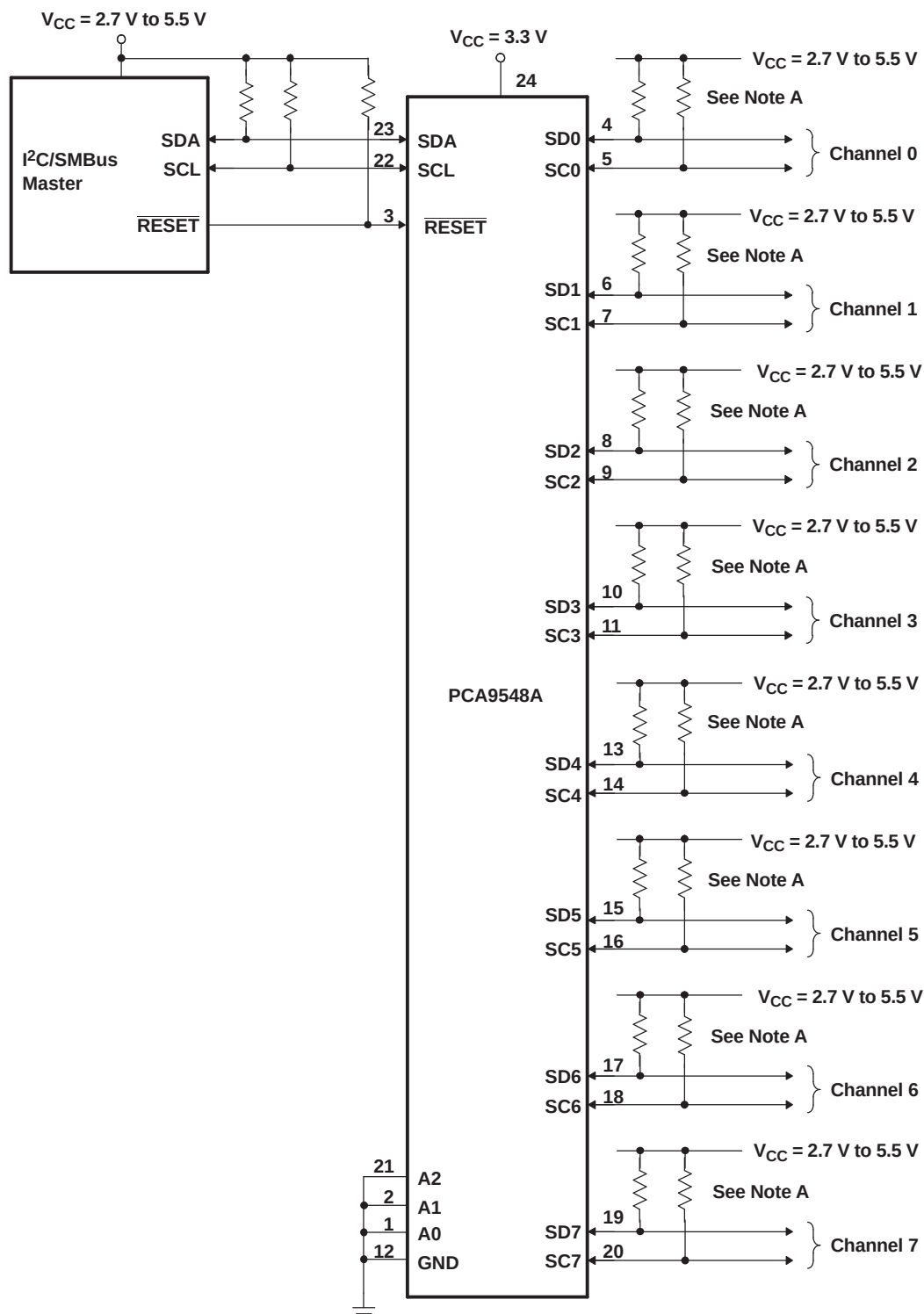
### 10.2 Typical Application

A typical application of the PCA9548A will contain 1 or many separate data pull-up voltages, V<sub>CC</sub>, one for the master device and one for each of the selectable slave channels, 0 through 7. In the event where the master device and all slave devices operate at the same voltage, then the VCC pin can be connected to this supply voltage. In an application where voltage translation is necessary, additional design requirements must be considered (See [Design Requirements](#)).

[Figure 10](#) shows an application in which the PCA9548A can be used.



**Typical Application (continued)**



A. Pin numbers shown are for the PW and RTW packages.

**Figure 10. PCA9548A Typical Application Schematic**

**PCA9548A**

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**Typical Application (continued)****10.2.1 Design Requirements**

The A0, A1, and A2 pins are hardware selectable to control the slave address of the PCA9548A. These pins may be tied directly to GND or  $V_{CC}$  in the application.

If multiple slave channels will be activated simultaneously in the application, then the total  $I_{OL}$  from SCL/SDA to GND on the master side will be the sum of the currents through all pull-up resistors,  $R_p$ .

The pass-gate transistors of the PCA9548A are constructed such that the  $V_{CC}$  voltage can be used to limit the maximum voltage that is passed from one I<sup>2</sup>C bus to another.

Figure 11 shows the voltage characteristics of the pass-gate transistors (note that the graph was generated using data specified in the [Electrical Characteristics](#) section of this data sheet). In order for the PCA9548A to act as a voltage translator, the  $V_{pass}$  voltage must be equal to or lower than the lowest bus voltage. For example, if the main bus is running at 5 V and the downstream buses are 3.3 V and 2.7 V,  $V_{pass}$  must be equal to or below 2.7 V to effectively clamp the downstream bus voltages. As shown in Figure 11,  $V_{pass(max)}$  is 2.7 V when the PCA9548A supply voltage is 4 V or lower, so the PCA9548A supply voltage could be set to 3.3 V. Pull-up resistors then can be used to bring the bus voltages to their appropriate levels (see Figure 10).

**10.2.2 Detailed Design Procedure**

Once all the slaves are assigned to the appropriate slave channels and bus voltages are identified, the pull-up resistors,  $R_p$ , for each of the buses need to be selected appropriately. The minimum pull-up resistance is a function of the reference voltage of the specific I<sup>2</sup>C channel ( $V_{DPUX}$ ),  $V_{OL(max)}$ , and  $I_{OL}$ :

$$R_{p(min)} = \frac{V_{DPUX} - V_{OL(max)}}{I_{OL}} \quad (1)$$

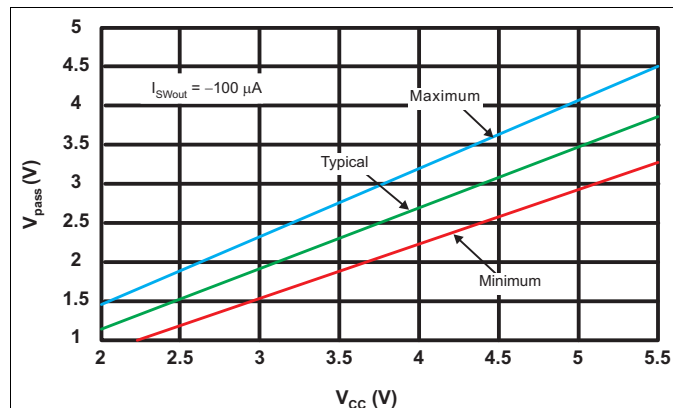
The maximum pull-up resistance is a function of the maximum rise time,  $t_r$  (300 ns for fast-mode operation,  $f_{SCL} = 400$  kHz) and bus capacitance,  $C_b$ :

$$R_{p(max)} = \frac{t_r}{0.8473 \times C_b} \quad (2)$$

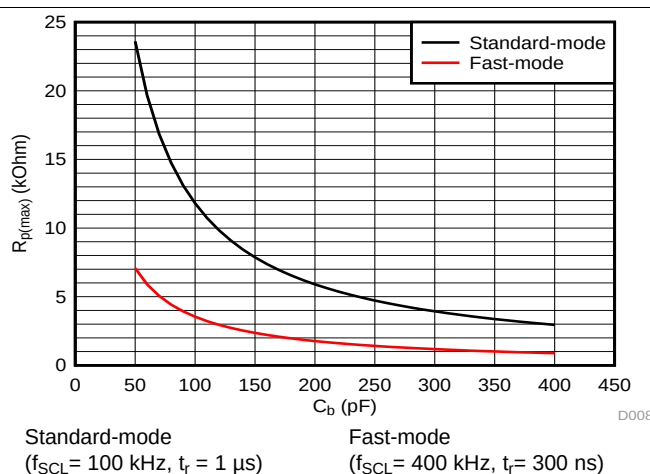
The maximum bus capacitance for an I<sup>2</sup>C bus must not exceed 400 pF for fast-mode operation. The bus capacitance can be approximated by adding the capacitance of the PCA9548A,  $C_{io(OFF)}$ , the capacitance of wires/connections/traces, and the capacitance of each individual slave on a given channel. If multiple channels will be activated simultaneously, each of the slaves on all channels will contribute to total bus capacitance.

## Typical Application (continued)

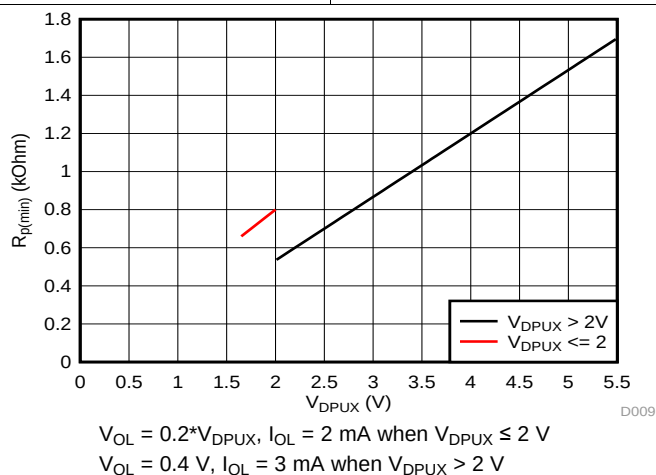
### 10.2.3 PCA9548A Application Curves



**Figure 11. Pass-Gate Voltage ( $V_{pass}$ ) vs Supply Voltage ( $V_{cc}$ ) at Three Temperature Points**



**Figure 12. Maximum Pull-Up resistance ( $R_{p(max)}$ ) vs Bus Capacitance ( $C_b$ )**



**Figure 13. Minimum Pull-Up Resistance ( $R_{p(min)}$ ) vs Pull-Up Reference Voltage ( $V_{DPUX}$ )**

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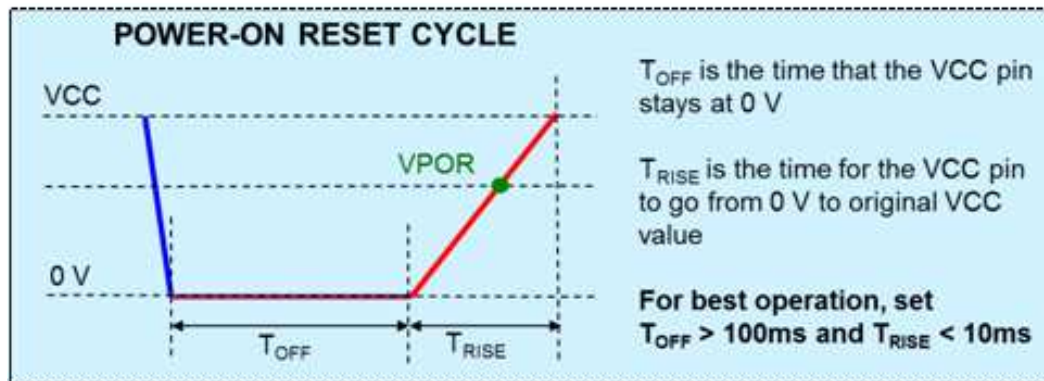
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## 11 Power Supply Recommendations

The operating power-supply voltage range of the PCA9548A is 2.3 V to 5.5 V applied at the VCC pin. When the PCA9548A is powered on for the first time or anytime the device needs to be reset by cycling the power supply, the power-on reset requirements must be followed to ensure the I<sup>2</sup>C bus logic is initialized properly.

### 11.1 Power-On Reset Errata

A power-on reset condition can be missed if the VCC ramps are outside specification listed below.



#### System Impact

If ramp conditions are outside timing allowances above, POR condition can be missed, causing the device to lock up.

## 12 Layout

### 12.1 Layout Guidelines

For PCB layout of the PCA9548A, common PCB layout practices should be followed but additional concerns related to high-speed data transfer such as matched impedances and differential pairs are not a concern for I<sup>2</sup>C signal speeds. It is common to have a dedicated ground plane on an inner layer of the board and pins that are connected to ground should have a low-impedance path to the ground plane in the form of wide polygon pours and multiple vias. By-pass and de-coupling capacitors are commonly used to control the voltage on the VCC pin, using a larger capacitor to provide additional power in the event of a short power supply glitch and a smaller capacitor to filter out high-frequency ripple.

In an application where voltage translation is not required, all  $V_{DPUX}$  voltages and  $V_{CC}$  could be at the same potential and a single copper plane could connect all of pull-up resistors to the appropriate reference voltage. In an application where voltage translation is required,  $V_{DPU0}$  and  $V_{DPU0}-V_{DPU7}$  may all be on the same layer of the board with split planes to isolate different voltage potentials.

To reduce the total I<sup>2</sup>C bus capacitance added by PCB parasitics, data lines (SCn and SDn) should be as short as possible and the widths of the traces should also be minimized (e.g. 5-10 mils depending on copper weight).

## 13 Device and Documentation Support

### 13.1 Trademarks

All trademarks are the property of their respective owners.

### 13.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 13.3 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| PCA9548ADB       | ACTIVE        | SSOP         | DB                 | 24   | 60             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PD548A                  | <a href="#">Samples</a> |
| PCA9548ADBG4     | ACTIVE        | SSOP         | DB                 | 24   | 60             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PD548A                  | <a href="#">Samples</a> |
| PCA9548ADBR      | ACTIVE        | SSOP         | DB                 | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PD548A                  | <a href="#">Samples</a> |
| PCA9548ADBRG4    | ACTIVE        | SSOP         | DB                 | 24   |                | TBD                        | Call TI                 | Call TI              | -40 to 85    |                         | <a href="#">Samples</a> |
| PCA9548ADGV      | NRND          | TVSOP        | DGV                | 24   |                | TBD                        | Call TI                 | Call TI              | -40 to 85    |                         |                         |
| PCA9548ADGVR     | ACTIVE        | TVSOP        | DGV                | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PD548A                  | <a href="#">Samples</a> |
| PCA9548ADGVRG4   | ACTIVE        | TVSOP        | DGV                | 24   |                | TBD                        | Call TI                 | Call TI              | -40 to 85    |                         | <a href="#">Samples</a> |
| PCA9548ADW       | ACTIVE        | SOIC         | DW                 | 24   | 25             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PCA9548A                | <a href="#">Samples</a> |
| PCA9548ADWG4     | ACTIVE        | SOIC         | DW                 | 24   | 25             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PCA9548A                | <a href="#">Samples</a> |
| PCA9548ADWR      | ACTIVE        | SOIC         | DW                 | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PCA9548A                | <a href="#">Samples</a> |
| PCA9548ADWRG4    | ACTIVE        | SOIC         | DW                 | 24   |                | TBD                        | Call TI                 | Call TI              | -40 to 85    |                         | <a href="#">Samples</a> |
| PCA9548APW       | NRND          | TSSOP        | PW                 | 24   | 60             | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PD548A                  |                         |
| PCA9548APWG4     | NRND          | TSSOP        | PW                 | 24   |                | TBD                        | Call TI                 | Call TI              | -40 to 85    |                         |                         |
| PCA9548APWR      | NRND          | TSSOP        | PW                 | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PD548A                  |                         |
| PCA9548APWRG4    | NRND          | TSSOP        | PW                 | 24   | 2000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | PD548A                  |                         |
| PCA9548ARGER     | NRND          | VQFN         | RGE                | 24   | 3000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-2-260C-1 YEAR  | -40 to 85    | PD548A                  |                         |
| PCA9548ARGERG4   | NRND          | VQFN         | RGE                | 24   |                | TBD                        | Call TI                 | Call TI              | -40 to 85    |                         |                         |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

---

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

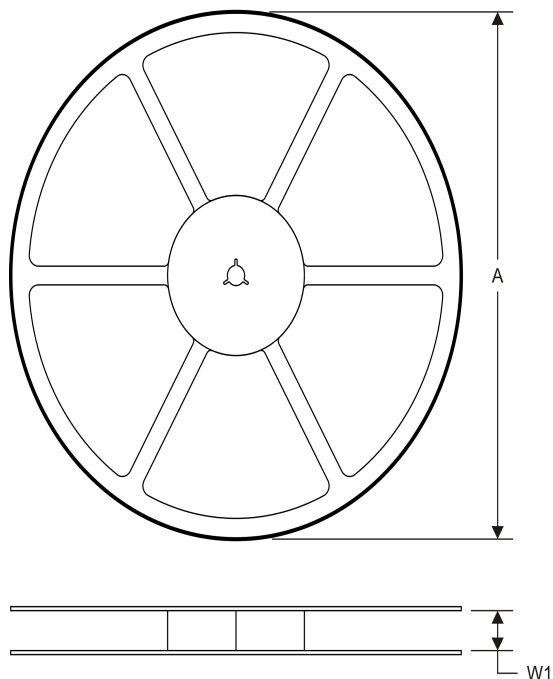
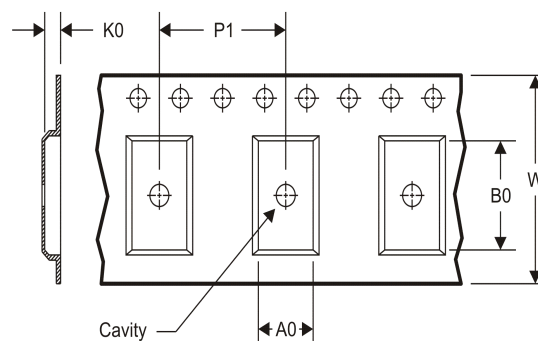
<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


|    |                                                           |
|----|-----------------------------------------------------------|
| A0 | Dimension designed to accommodate the component width     |
| B0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

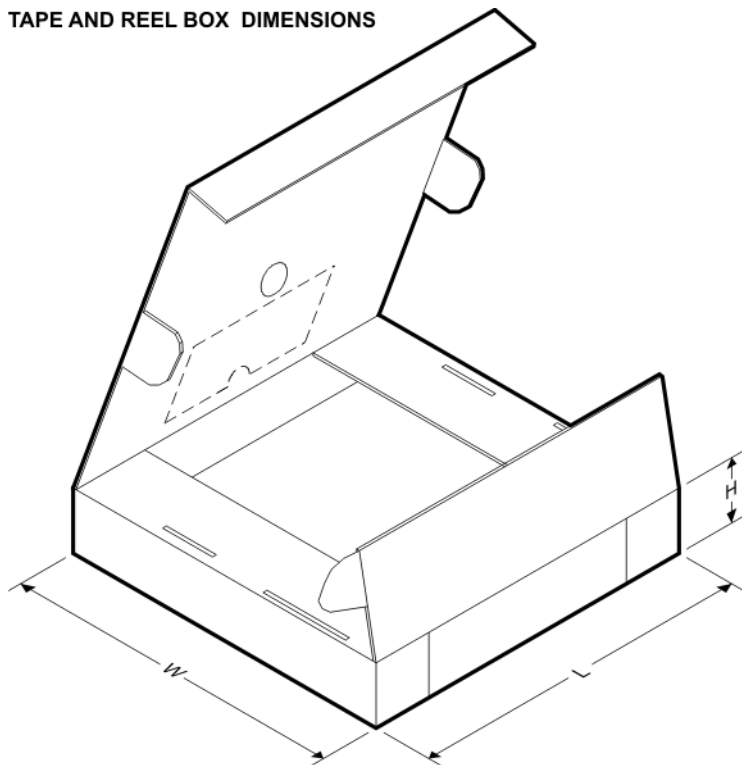
**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| PCA9548ADBR  | SSOP         | DB              | 24   | 2000 | 330.0              | 16.4               | 8.2     | 8.8     | 2.5     | 12.0    | 16.0   | Q1            |
| PCA9548ADGVR | TVSOP        | DGV             | 24   | 2000 | 330.0              | 12.4               | 6.9     | 5.6     | 1.6     | 8.0     | 12.0   | Q1            |
| PCA9548ADWR  | SOIC         | DW              | 24   | 2000 | 330.0              | 24.4               | 10.75   | 15.7    | 2.7     | 12.0    | 24.0   | Q1            |
| PCA9548APWR  | TSSOP        | PW              | 24   | 2000 | 330.0              | 16.4               | 6.95    | 8.3     | 1.6     | 8.0     | 16.0   | Q1            |
| PCA9548ARGER | VQFN         | RGE             | 24   | 3000 | 330.0              | 12.4               | 4.25    | 4.25    | 1.15    | 8.0     | 12.0   | Q2            |



## TAPE AND REEL BOX DIMENSIONS

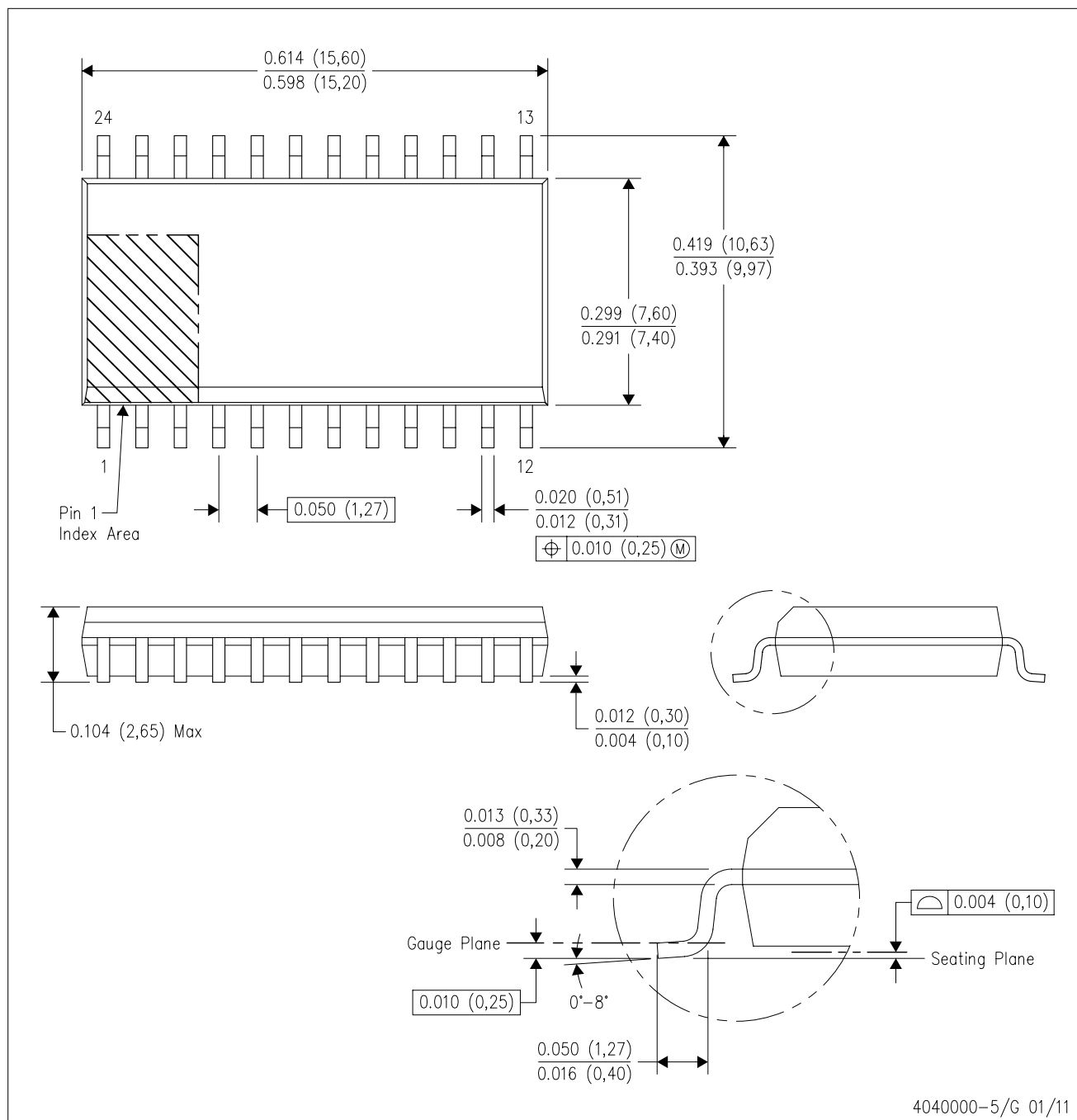


\*All dimensions are nominal

| Device       | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| PCA9548ADBR  | SSOP         | DB              | 24   | 2000 | 367.0       | 367.0      | 38.0        |
| PCA9548ADGVR | TVSOP        | DGV             | 24   | 2000 | 367.0       | 367.0      | 35.0        |
| PCA9548ADWR  | SOIC         | DW              | 24   | 2000 | 367.0       | 367.0      | 45.0        |
| PCA9548APWR  | TSSOP        | PW              | 24   | 2000 | 367.0       | 367.0      | 38.0        |
| PCA9548ARGER | VQFN         | RGE             | 24   | 3000 | 367.0       | 367.0      | 35.0        |

DW (R-PDSO-G24)

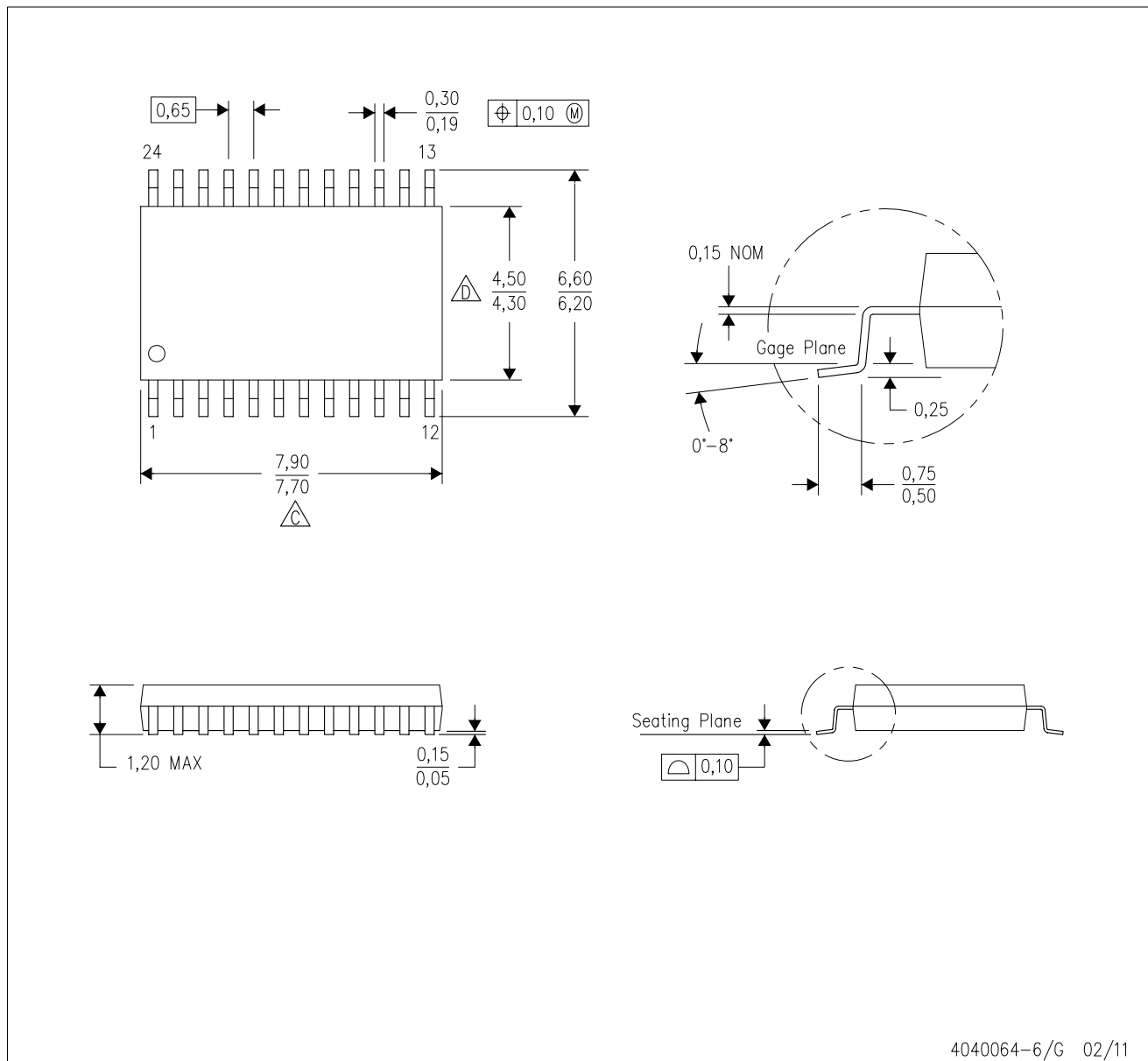
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-013 variation AD.

PW (R-PDSO-G24)

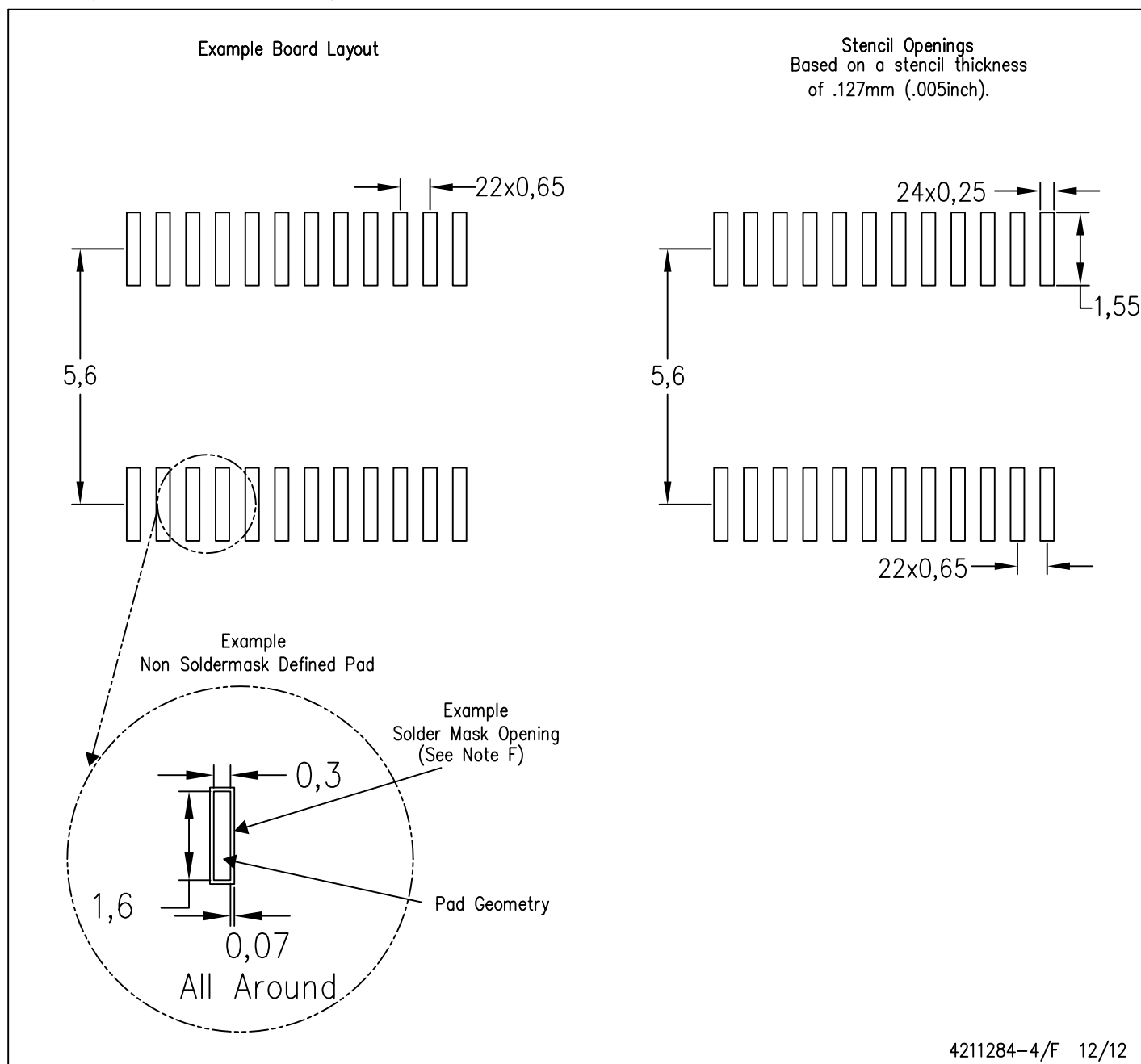
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G24)

PLASTIC SMALL OUTLINE

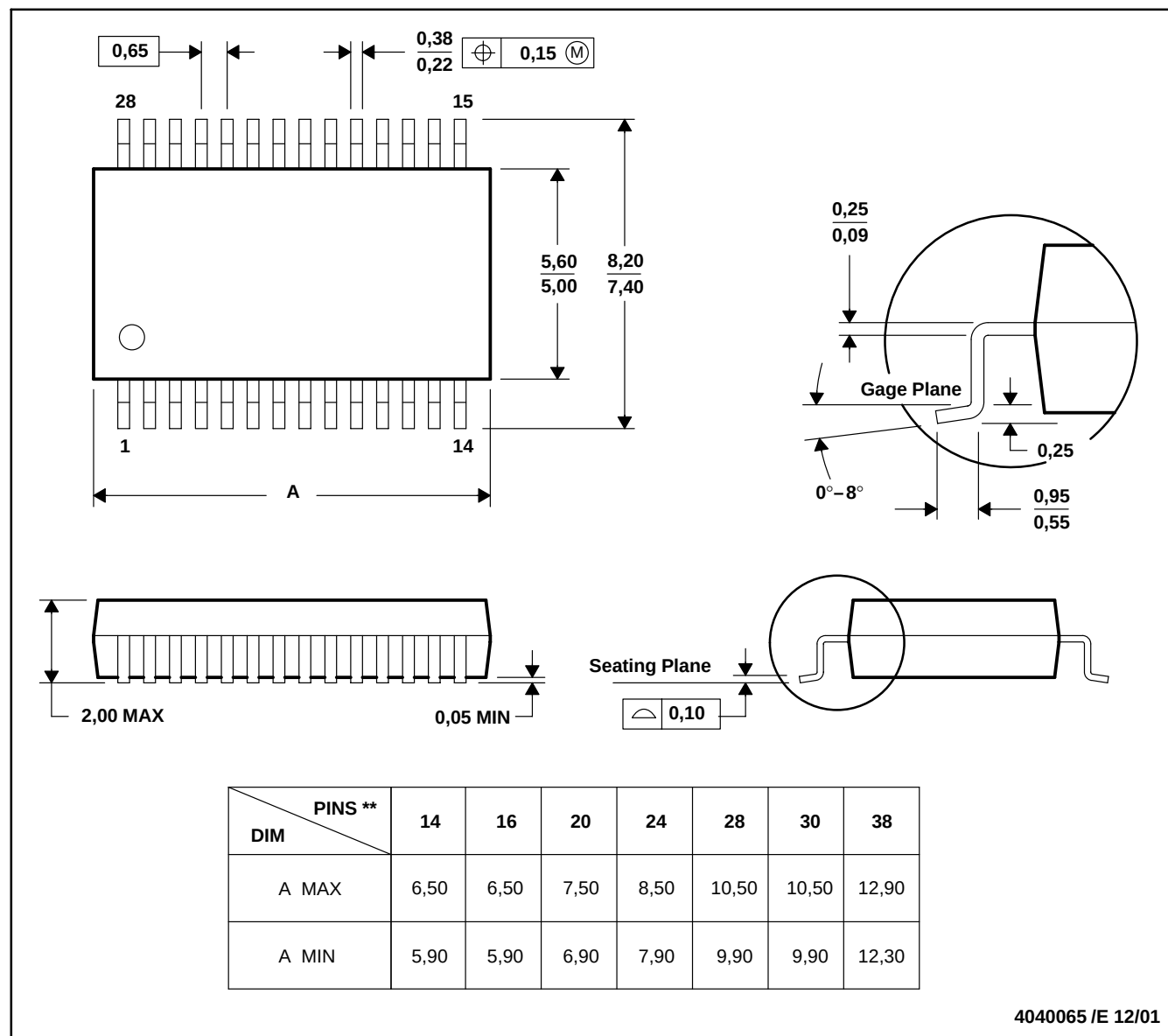


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

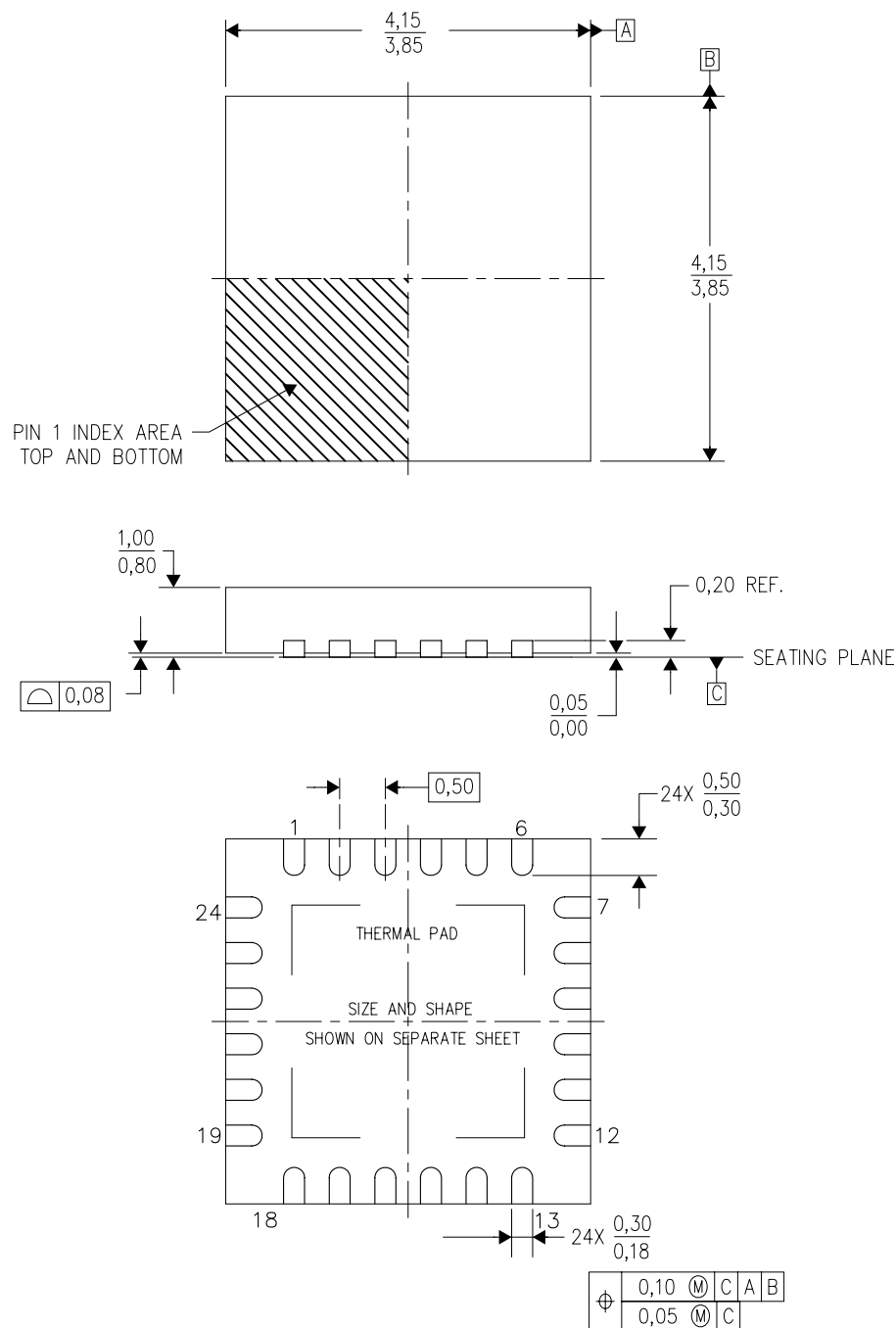
28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

RGE (S-PVQFN-N24)

PLASTIC QUAD FLATPACK NO-LEAD



4204104/G 07/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Quad Flatpack, No-Leads (QFN) package configuration.
  - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
  - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - F. Falls within JEDEC MO-220.

RGE (S-PVQFN-N24)

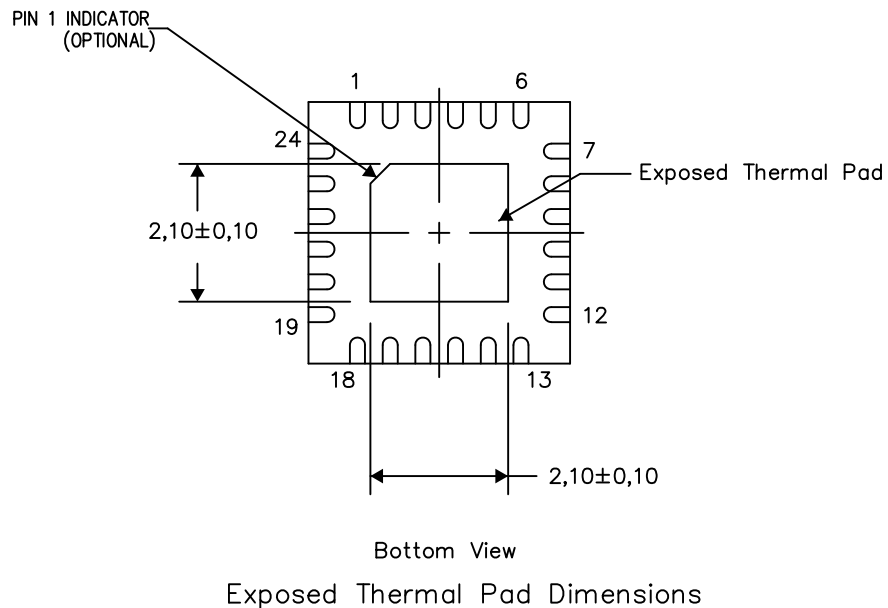
PLASTIC QUAD FLATPACK NO-LEAD

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.

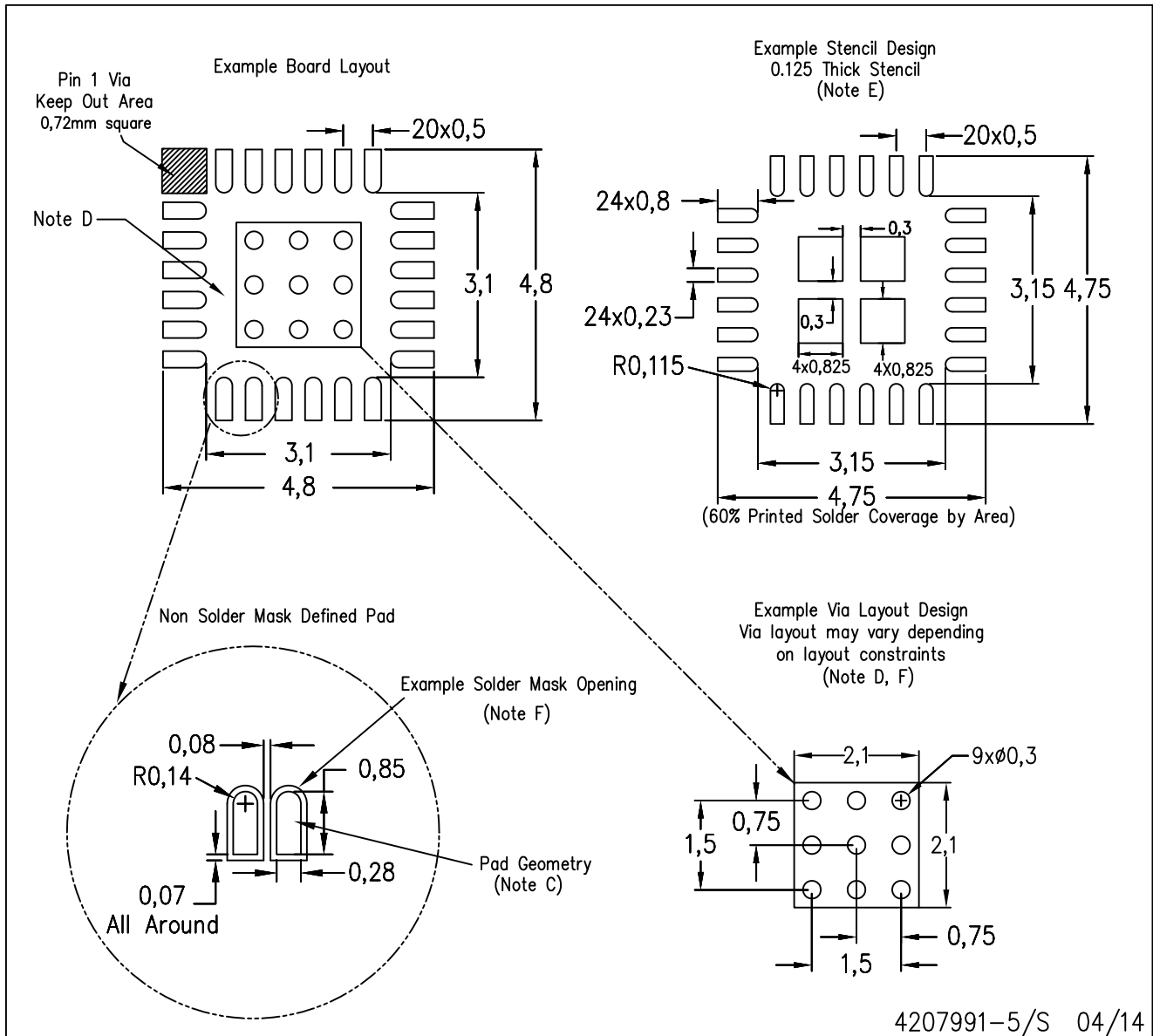


4206344-6/AG 04/14

NOTES: A. All linear dimensions are in millimeters

RGE (S-PVQFN-N24)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
  - F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.



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